Westlake Polymers

Enhancing your life every day

EC850

EC850AA = E6838-850P

Application/Uses

- Coatings for paper/paperboard
- Food contact applications

Product Description

WESTLAKE low-density polyethylene EC850 is a resin designed for applications where high coating speeds and good drawdown are required. The combination of high melt index and low density provides good heat seals at high packaging or sealing rates. It also demonstrates good adhesion to paper, provides a good moisture barrier, and is heat-sealable at low temperatures.

Typical Physical Properties

Property[a]		Test[b] Method	Typical Value, Units[c]
Melt Index (Condition 190°C/2.16 kg)		D 1238	12.5 g/10 min
Density		D 4883	915 kg/m^3 (0.915 g/cm^3)
Tensile Stress @ Break	500 mm/min (20 in./min)	D 638 Type IV	9.7 MPa (1400 psi)
Elongation @ Break	500 mm/min (20 in./min)	D 638 Type IV	400%
Flexural Modulus	(2% Secant) 12.7 mm/min (0.5 in./min)	D 790	172 MPa (25,000 psi)

[a] *Unless noted otherwise, all tests are run at 23°C (73°F) and 50% relative humidity.*
[b] *Unless noted otherwise, the test method is ASTM.*
[c] *Units are in SI or US customary units.*

NOTES
Where required, test specimens are compression molded according to ASTM D1928.

FDA
This product has some 21 CFR clearances. Please contact Westlake Product Regulatory Department for statements.

PROCESSING
Melt temperatures of 300° F - 330° F are recommended for Westlake EC850.

COMMENTS
Properties reported here are based on limited testing. Westlake makes no representation that the material in any particular shipment will conform exactly to the values given.